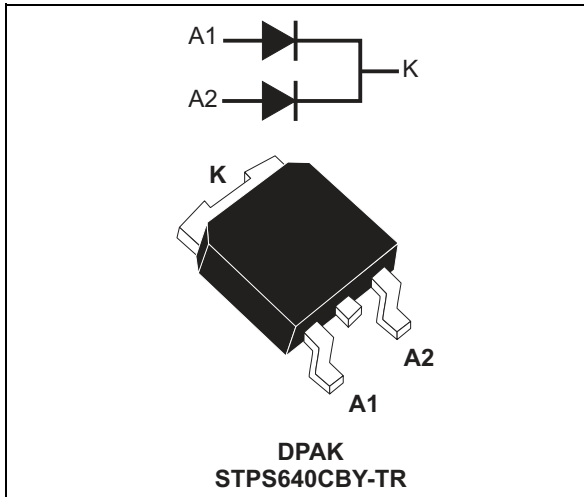


Automotive power Schottky rectifier

Datasheet – production data



Features

- Low forward voltage drop
- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- AEC-Q101 qualified.

Description

This dual Schottky rectifier is designed for switch mode power supplies and other power converters.

This device is intended for use in low and medium voltage operation, and in particular high frequency circuits where low switching losses are required (free wheeling and polarity protection) in automotive applications.

Table 1. Device summary

| Symbol | Value |
|-------------|---------|
| $I_{F(AV)}$ | 2 x 3 A |
| V_{RRM} | 40 V |
| T_j | 150 °C |
| $V_F (Typ)$ | 0.50 V |

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

| Symbol | Parameter | | Value | Unit |
|--------------|---|---|-------------|------|
| V_{RRM} | Repetitive peak reverse voltage | | 40 | V |
| $I_{F(RMS)}$ | Forward rms current | | 6 | A |
| $I_{F(AV)}$ | Average forward current, $\delta = 0.5$, $T_c = 135\text{ °C}$ | per diode | 3 | A |
| | | per device | 6 | |
| I_{FSM} | Surge non repetitive forward current | $t_p = 10\text{ ms}$ sinusoidal, $T_c = 25\text{ °C}$ | 75 | A |
| I_{RRM} | Peak repetitive reverse current | $t_p = 2\text{ }\mu\text{s}$, $F = 1\text{ kHz}$ | 1 | A |
| P_{ARM} | Repetitive peak avalanche power | $t_p = 1\text{ }\mu\text{s}$, $T_c = 25\text{ °C}$ | 1300 | W |
| T_{stg} | Storage temperature range | | -65 to +150 | °C |
| T_j | Operating junction temperature | | -40 to +150 | °C |

Table 3. Thermal parameters

| Symbol | Parameter | | Value | Unit |
|---------------|------------------|------------|-------|------|
| $R_{th(j-c)}$ | Junction to case | per diode | 5.5 | °C/W |
| | | per device | 3 | |
| $R_{th(c)}$ | coupling | | 0.5 | |

When the diodes 1 and 2 are used simultaneously :
 $\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$

Table 4. Static electrical characteristics (per diode)

| Symbol | Parameter | Test conditions | | Min. | Typ | Max. | Unit |
|-------------|-------------------------|-----------------------|--------------------|------|------|------|---------------|
| $I_R^{(1)}$ | Reverse leakage current | $T_j = 25\text{ °C}$ | $V_R = V_{RRM}$ | - | - | 100 | μA |
| | | $T_j = 125\text{ °C}$ | | - | 2 | 10 | mA |
| $V_F^{(2)}$ | Forward voltage drop | $T_j = 25\text{ °C}$ | $I_F = 3\text{ A}$ | - | - | 0.63 | V |
| | | $T_j = 125\text{ °C}$ | | - | 0.50 | 0.57 | |
| | | $T_j = 25\text{ °C}$ | $I_F = 6\text{ A}$ | - | - | 0.84 | |
| | | $T_j = 125\text{ °C}$ | | - | 0.67 | 0.72 | |

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$
2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:
 $P = 0.42 \times I_{F(AV)} + 0.050 \times I_{F(RMS)}^2$

Figure 1. Average forward power dissipation versus average forward current (per diode)

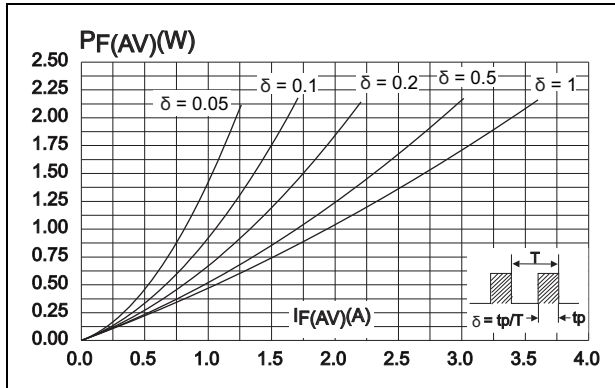


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

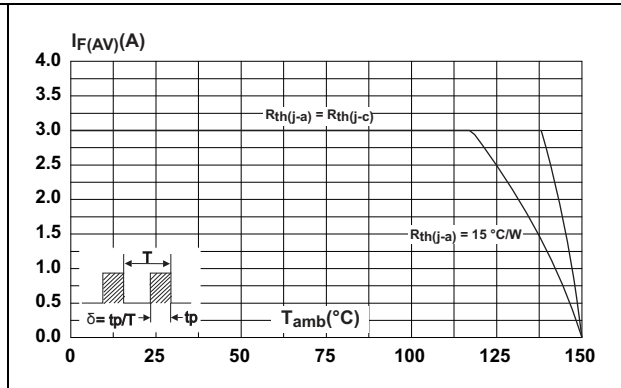


Figure 3. Normalized avalanche power derating versus pulse duration

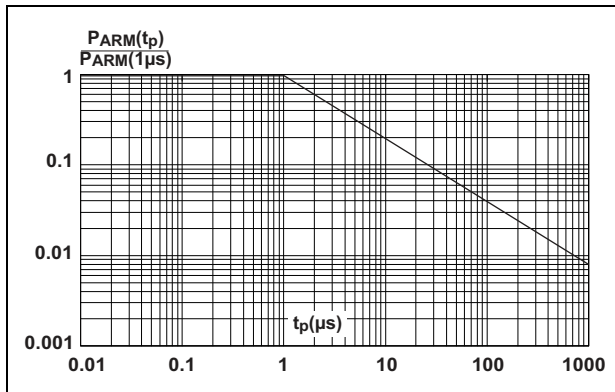


Figure 4. Normalized avalanche power derating versus junction temperature

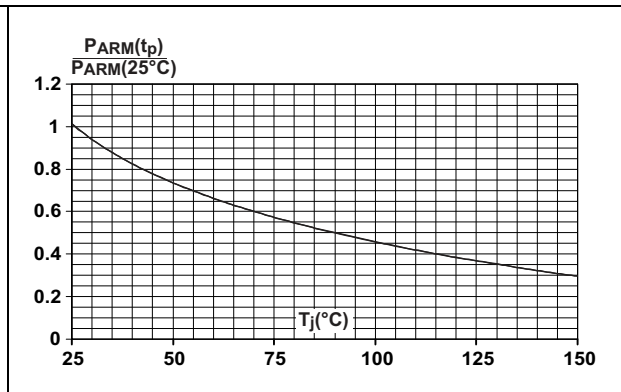


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

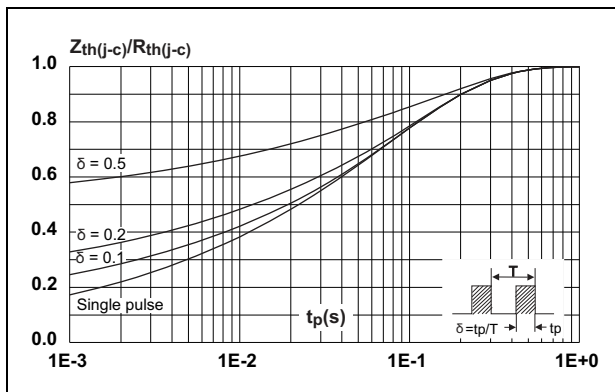


Figure 6. Reverse leakage current vs. reverse voltage applied (typical values, per diode)

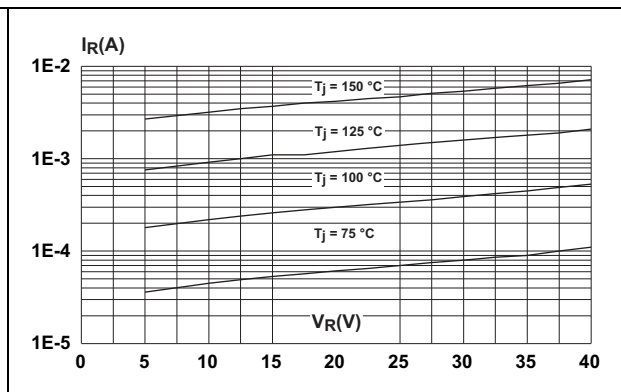


Figure 7. Junction capacitance vs. reverse voltage applied (typical values, per diode)

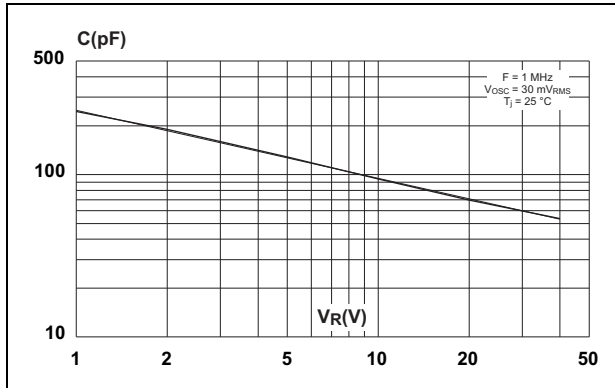


Figure 8. Forward voltage drop vs. forward current (per diode)

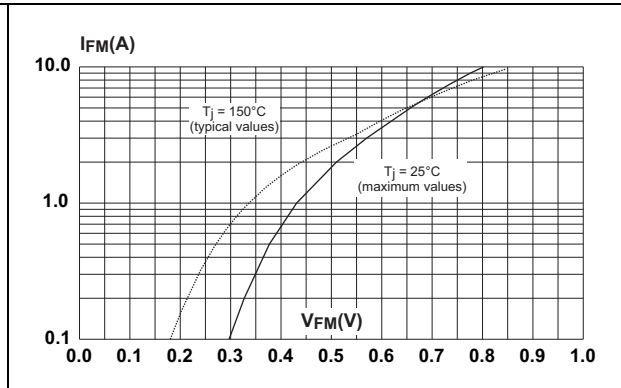
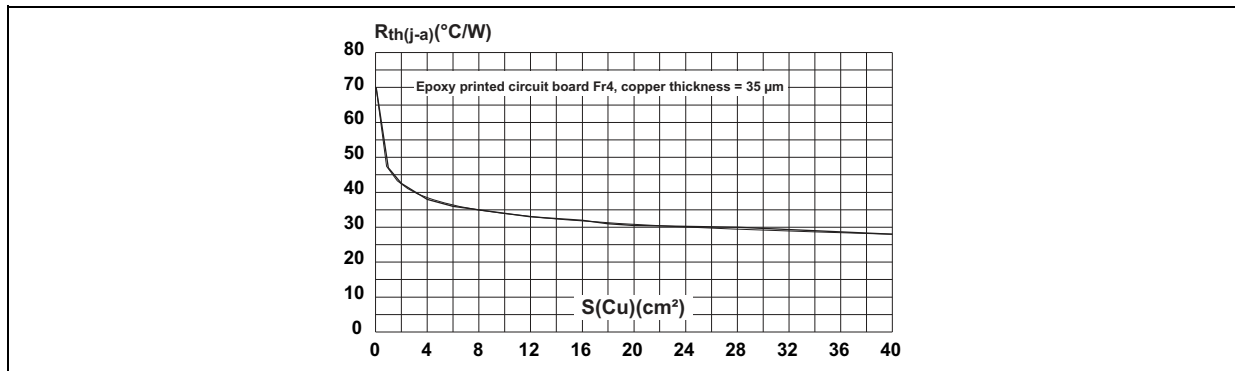


Figure 9. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

- Epoxy meets UL94,V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 10. DPAK dimension definitions

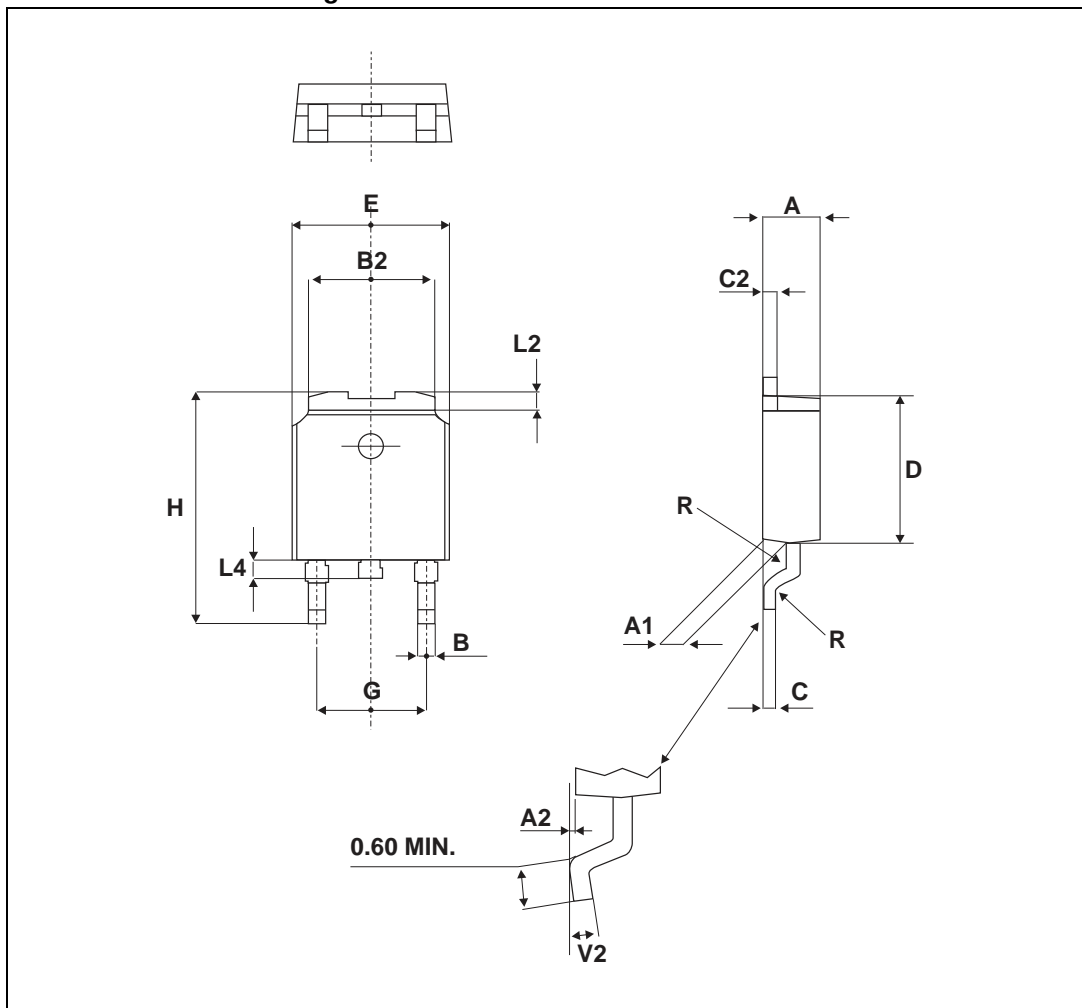
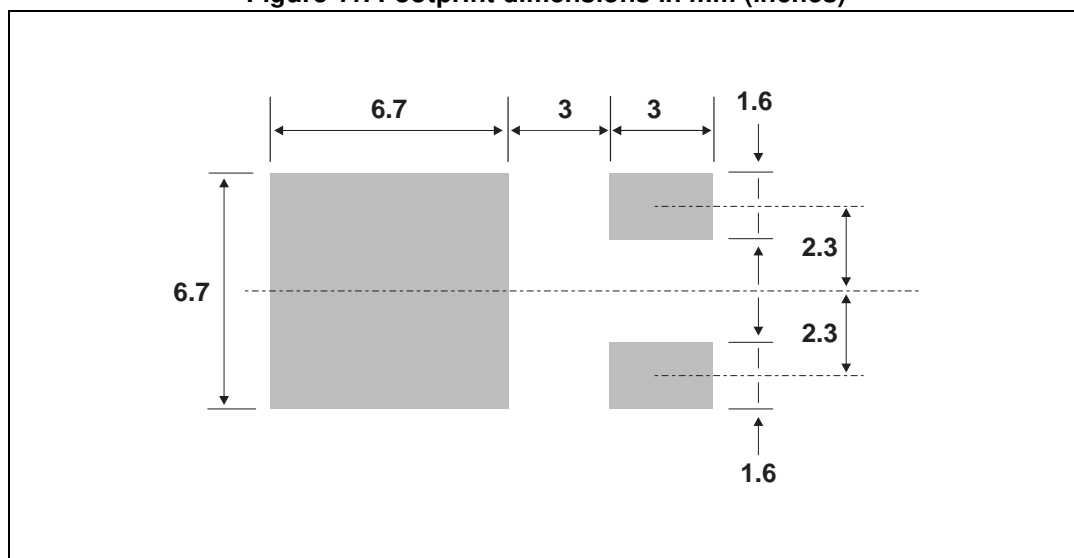


Table 5. DPAK dimension values

| Ref. | Dimensions | | | | | |
|------|-------------|-----------|-------|--------|------------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 | 0.086 | | 0.094 |
| A1 | 0.90 | | 1.10 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.90 | 0.025 | | 0.035 |
| B2 | 5.20 | | 5.40 | 0.204 | | 0.212 |
| C | 0.45 | | 0.60 | 0.017 | | 0.023 |
| C2 | 0.48 | | 0.60 | 0.018 | | 0.023 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.60 | 0.251 | | 0.259 |
| G | 4.40 | | 4.60 | 0.173 | | 0.181 |
| H | 9.35 | | 10.10 | 0.368 | | 0.397 |
| L2 | | 0.80 typ. | | | 0.031 typ. | |
| L4 | 0.60 | | 1.00 | 0.023 | | 0.039 |
| V2 | 0° | | 8° | 0° | | 8° |

Figure 11. Footprint dimensions in mm (inches)



3 Ordering information

Table 6. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|-----------|---------|--------|----------|---------------|
| STPS640CBY-TR | STPS640CY | DPAK | 0.3 g | 2500 | Tape and reel |

4 Revision history

Table 7. Revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 6-Nov-2013 | 1 | First issue |
| 04-Dec-2013 | 2 | Properties changed from preliminary data to production data. |

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